

MOS CAPACITOR CHIPS 0.3 PF to 330 PF

- 0.3 PF to 330 PF • Gold Backed • Aluminum Bonding Pads • Low Leakage Currents
- High Temperature Stability • Available in Chip or Slice Form

The Dionics series of MOS chip capacitors are economical devices, specifically designed for hybrid circuit applications where reliability, physical size, and compatible bonding techniques are of prime consideration.

Each chip is gold backed and may be eutectically bonded with the chip bottom serving as one plate contact. An aluminum pad on the top of the chip surface is then contacted, using conventional wire bonding techniques.

In the case of the dual units, both capacitor values may be used separately with the underside of the chip serving as a common plate for both. By stitch bonding the surface pads together, it is possible to

parallel both units to obtain a higher capacitance value.

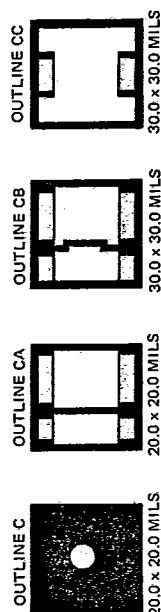
By making electrical contact only to the two surface bonding pads, the two capacitors are placed in series, thus obtaining a lower capacitance value than either individual capacitor would offer.

The inherent advantages that MOS capacitors offer when compared to their ceramic equivalents are a smaller physical size, increased high temperature stability, and lower leakage currents.

Custom values are available within the range of 0.3 PF to 330 PF, while custom arrays can be supplied with multiple capacitors within each chip.

SINGLE VALUES (NEW VALUES†) (STANDARD RMA VALUES*)

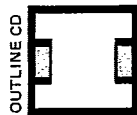
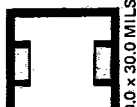
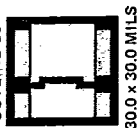
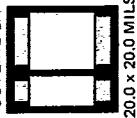
Part No.	Value Capacitor	Maximum Working Voltage	Probed Voltage	Part No.	Value Capacitor	Maximum Working Voltage	Probed Voltage
*† C0.3	0.3pf	75 V	150 V	† CD82	82pf	50 V	100 V
C0.5	0.5pf	75 V	150 V	CD100	100pf	50 V	100 V
C1.0	1.0pf	75 V	150 V	† CD150	150pf	50 V	100 V
† C1.5	1.5pf	75 V	150 V	† CH120	120pf	100 V	200 V
† C2.0	2.0pf	75 V	150 V	† CH130	130pf	100 V	200 V
† C2.5	2.5pf	75 V	150 V	CH150	150pf	100 V	200 V
CF3.0	3.0pf	100 V	200 V	† CE100	100pf	50 V	100 V
CF6.8	6.8pf	100 V	200 V	*† CE180	180pf	50 V	100 V
CF10	10pf	100 V	200 V	† CE190	190pf	50 V	100 V
† CG15	15pf	100 V	200 V	CE200	200pf	50 V	100 V
† CG18	18pf	100 V	200 V	† CE220	220pf	50 V	100 V
CG22	22pf	100 V	200 V	CI200	200pf	100 V	200 V
CG27	27pf	100 V	200 V	CI800	300pf	50 V	100 V
CG30	30pf	100 V	200 V	* CI830	330pf	50 V	100 V
CG33	33pf	100 V	200 V	MULTIPLE VALUES			
† CG36	36pf	100 V	200 V				
† CG39	39pf	100 V	200 V	CA3-4.5	3 pf & 4.5 pf	75 V	150 V
† CG43	43pf	100 V	200 V	CA 7-10	7 pf & 10 pf	50 V	100 V
† CG47	47pf	100 V	200 V	CA 10-15	10 pf & 15 pf	25 V	50 V
† CG50	50pf	100 V	200 V	CA 20-33	20 pf & 33 pf	50 V	100 V
*† CG51	51pf	100 V	200 V	CA 35-60	35 pf & 60 pf	25 V	50 V
† CG56	56pf	100 V	200 V	CA 1248	1,2,4,8pf	50 V	100 V
† CG60	60pf	100 V	200 V	C 300	3,7,20 pf	25 V	50 V
*† CG62	62pf	100 V	200 V	C 322	10,22,22, pf	100 V	200 V
CG68	68pf	50 V	100 V	C 454	4,8,16,54,pf	50 V	100 V
† CD50	50pf	50 V	100 V	C 500	56,0,20,40,80 pf	50 V	100 V
*† CD51	51pf	50 V	100 V	C 516	1,2,4,8,16 pf	50 V	100 V
*† CD56	56pf	50 V	100 V	C 700	1,2,5,10,10,27,39 pf	50V	100 V



OUTLINE CA

OUTLINE CB

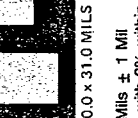
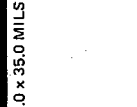
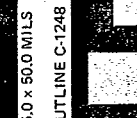
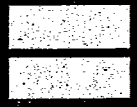
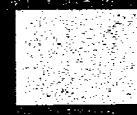
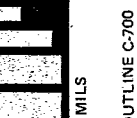
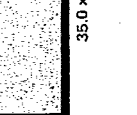
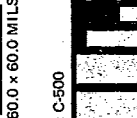
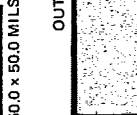
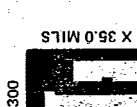
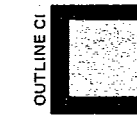
OUTLINE CC



OUTLINE CK

OUTLINE CL

OUTLINE CM



Typical Thickness 6 Mils $\pm$ 1 Mil
 Tolerance = $\pm$ 10% with 2% within a lot
 Temperature Coefficient = $\pm$ 35 PPM $\pm$ 15 PPM/ $^{\circ}$ C
 Dissipation Factor = 0.001 to 0.0025 from -20° C to $+150^{\circ}$ C
 Maximum Operating Temperature — $+200^{\circ}$ C
 Typical Operating Temperature — -55 to $+125^{\circ}$ C
 Typical Storage Temperature — -55 to $+125^{\circ}$ C

